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#### Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

E·XFI

Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	30 MIPs
Connectivity	CANbus, I <sup>2</sup> C, SPI, UART/USART
Peripherals	AC'97, Brown-out Detect/Reset, I <sup>2</sup> S, LVD, POR, PWM, WDT
Number of I/O	52
Program Memory Size	144KB (48K x 24)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 16x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic30f6012a-30i-pf

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

## 2.4.2.4 Data Space Write Saturation

In addition to adder/subtracter saturation, writes to data space may also be saturated but without affecting the contents of the source accumulator. The data space write saturation logic block accepts a 16-bit, 1.15 fractional value from the round logic block as its input, together with overflow status from the original source (accumulator) and the 16-bit round adder. These are combined and used to select the appropriate 1.15 fractional value as output to write to data space memory.

If the SATDW bit in the CORCON register is set, data (after rounding or truncation) is tested for overflow and adjusted accordingly, For input data greater than 0x007FFF, data written to memory is forced to the maximum positive 1.15 value, 0x7FFF. For input data less than 0xFF8000, data written to memory is forced to the maximum negative 1.15 value, 0x8000. The MSb of the source (bit 39) is used to determine the sign of the operand being tested.

If the SATDW bit in the CORCON register is not set, the input data is always passed through unmodified under all conditions.

## 2.4.3 BARREL SHIFTER

The barrel shifter is capable of performing up to 16-bit arithmetic or logic right shifts, or up to 16-bit left shifts in a single cycle. The source can be either of the two DSP accumulators, or the X bus (to support multi-bit shifts of register or memory data).

The shifter requires a signed binary value to determine both the magnitude (number of bits) and direction of the shift operation. A positive value will shift the operand right. A negative value will shift the operand left. A value of '0' will not modify the operand.

The barrel shifter is 40 bits wide, thereby obtaining a 40-bit result for DSP shift operations and a 16-bit result for MCU shift operations. Data from the X bus is presented to the barrel shifter between bit positions 16 to 31 for right shifts, and bit positions 0 to 16 for left shifts.

## 3.2 Data Address Space

The core has two data spaces. The data spaces can be considered either separate (for some DSP instructions), or as one unified linear address range (for MCU instructions). The data spaces are accessed using two Address Generation Units (AGUs) and separate data paths.

#### 3.2.1 DATA SPACE MEMORY MAP

The data space memory is split into two blocks, X and Y data space. A key element of this architecture is that Y space is a subset of X space, and is fully contained within X space. In order to provide an apparent linear addressing space, X and Y spaces have contiguous addresses.

When executing any instruction other than one of the MAC class of instructions, the X block consists of the 64 Kbyte data address space (including all Y addresses). When executing one of the MAC class of instructions, the X block consists of the 64 Kbyte data address space excluding the Y address block (for data reads only). In other words, all other instructions regard the entire data memory as one composite address space. The MAC class instructions extract the Y address space from data space and address it using EAs sourced from W10 and W11. The remaining X data space is addressed using W8 and W9. Both address spaces are concurrently accessed only with the MAC class instructions.

The data space memory maps are shown in Figure 3-8 and Figure 3-9.

## 3.2.2 DATA SPACES

The X data space is used by all instructions and supports all Addressing modes. There are separate read and write data buses. The X read data bus is the return data path for all instructions that view data space as combined X and Y address space. It is also the X address space data path for the dual operand read instructions (MAC class). The X write data bus is the only write path to data space for all instructions.

The X data space also supports Modulo Addressing for all instructions, subject to addressing mode restrictions. Bit-Reversed Addressing is only supported for writes to X data space.

The Y data space is used in concert with the X data space by the MAC class of instructions (CLR, ED, EDAC, MAC, MOVSAC, MPY, MPY.N and MSC) to provide two concurrent data read paths. No writes occur across the Y bus. This class of instructions dedicates two W register pointers, W10 and W11, to always address Y data space, independent of X data space, whereas W8 and W9 always address X data space. Note that during accumulator write back, the data address space is considered a combination of X and Y data spaces, so the write occurs across the X bus. Consequently, the write can be to any address in the entire data space.

The Y data space can only be used for the data prefetch operation associated with the MAC class of instructions. It also supports Modulo Addressing for automated circular buffers. Of course, all other instructions can access the Y data address space through the X data path as part of the composite linear space.

The boundary between the X and Y data spaces is defined as shown in Figure 3-7 and Figure 3-8 and is not user programmable. Should an EA point to data outside its own assigned address space, or to a location outside physical memory, an all zero word/byte will be returned. For example, although Y address space is visible by all non-MAC instructions using any addressing mode, an attempt by a MAC instruction to fetch data from that space using W8 or W9 (X space pointers) will return 0x0000.

#### FIGURE 3-9: DATA SPACE FOR MCU AND DSP (MAC CLASS) INSTRUCTIONS EXAMPLE



# TABLE 3-2:EFFECT OF INVALID<br/>MEMORY ACCESSES

Attempted Operation	Data Returned
EA = an unimplemented address	0x0000 <sup>(1)</sup>
W8 or W9 used to access Y data space in a MAC instruction	0x0000
W10 or W11 used to access X data space in a MAC instruction	0x0000

Note 1: An address error trap is generated when an unimplemented memory address is accessed.

All effective addresses are 16 bits wide and point to bytes within the data space. Therefore, the data space address range is 64 Kbytes or 32K words.

#### 3.2.3 DATA SPACE WIDTH

The core data width is 16 bits. All internal registers are organized as 16-bit wide words. Data space memory is organized in byte addressable, 16-bit wide blocks.

## 3.2.4 DATA ALIGNMENT

To help maintain backward compatibility with PIC® MCU devices and improve data space memory usage efficiency, the dsPIC30F instruction set supports both word and byte operations. Data is aligned in data memory and registers as words, but all data space EAs resolve to bytes. Data byte reads will read the complete word which contains the byte, using the LSb of any EA to determine which byte to select. The selected byte is placed onto the LSB of the X data path (no byte accesses are possible from the Y data path as the MAC class of instruction can only fetch words). That is, data memory and registers are organized as two parallel byte wide entities with shared (word) address decode but separate write lines. Data byte writes only write to the corresponding side of the array or register which matches the byte address.

As a consequence of this byte accessibility, all Effective Address calculations (including those generated by the DSP operations which are restricted to word-sized data) are internally scaled to step through word aligned memory. For example, the core would recognize that Post-Modified Register Indirect Addressing mode [Ws++] will result in a value of Ws + 1 for byte operations and Ws + 2 for word operations.

# TABLE 3-3: CORE REGISTER MAP<sup>(1)</sup> (CONTINUED)

SFR Name	Address (Home)	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset State	
SR	0042	AO	OB	SA	SB	OAB	SAB	DA	DC	IPL2	IPL1	IPLO	RA	z	Vo	Z	υ	000 0000 0000 0000	0
CORCON	0044		I		SN	EDT	DL2	DL1	DLO	SATA	SATB	SATDW	ACCSAT	IPL3	PSV	RND	≝	0000 0000 0010 000	0
MODCON	0046	XMODEN	YMODEN	Ι	Ι		BWM	<3:0>			ΛWY	<3:0>			<b>™</b> M	<3:0>		000 0000 0000 0000	0
XMODSRT	0048							ΧS	<15:1>								0	nnn nnnn nnnn nnnn	0
XMODEND	004A							ХĘ	<15:1>								Ч	nnn nnnn nnnn nnnn	
YMODSRT	004C							ΥS	<15:1>								0	nnn nnnn nnnn nnnn	0
YMODEND	004E							ΥĘ	<15:1>								1	nnn nnnn nnnn nnnn	
XBREV	00200	BREN							ïX	3<14:0>								nnn nnnn nnnn nnnn	Þ
DISICNT	0052	I	I							DISICN	T<13:0>							000 0000 0000 0000	0
BSRAM	0750		Ι								1	1			IW_BSR	IR_BSR	RL_BSR	000 0000 0000 0000	0
SSRAM	0752		Ι		Ι			I	I	Ι	I	Ι			IW_SSR	IR_SSR	RL_SSR	0000 0000 0000 0000	0
Legend:	u = uniniti	ialized bit; —	- = unimplem	ented bit,	read as '0	•													1

Note 1: Refer to the "dsPIC30F Family Reference Manual" (DS70046) for descriptions of register bit fields.

# dsPIC30F6011A/6012A/6013A/6014A

NOTES:

## 6.6 **Programming Operations**

A complete programming sequence is necessary for programming or erasing the internal Flash in RTSP mode. A programming operation is nominally 2 msec in duration and the processor stalls (waits) until the operation is finished. Setting the WR bit (NVMCON<15>) starts the operation, and the WR bit is automatically cleared when the operation is finished.

#### 6.6.1 PROGRAMMING ALGORITHM FOR PROGRAM FLASH

The user can erase and program one row of program Flash memory at a time. The general process is:

- 1. Read one row of program Flash (32 instruction words) and store into data RAM as a data "image".
- 2. Update the data image with the desired new data.
- 3. Erase program Flash row.
  - a) Set up NVMCON register for multi-word, program Flash, erase, and set WREN bit.
  - b) Write address of row to be erased into NVMADRU/NVMADR.
  - c) Write 0x55 to NVMKEY.
  - d) Write 0xAA to NVMKEY.

EXAMPLE 6-1:

- e) Set the WR bit. This will begin erase cycle.
- f) CPU will stall for the duration of the erase cycle.
- g) The WR bit is cleared when erase cycle ends.

- Write 32 instruction words of data from data RAM "image" into the program Flash write latches.
- 5. Program 32 instruction words into program Flash.
  - a) Set up NVMCON register for multi-word, program Flash, program, and set WREN bit.
  - b) Write 0x55 to NVMKEY.
  - c) Write 0xAA to NVMKEY.
  - d) Set the WR bit. This will begin program cycle.
  - e) CPU will stall for duration of the program cycle.
  - f) The WR bit is cleared by the hardware when program cycle ends.
- 6. Repeat steps 1 through 5 as needed to program desired amount of program Flash memory.

# 6.6.2 ERASING A ROW OF PROGRAM MEMORY

Example 6-1 shows a code sequence that can be used to erase a row (32 instructions) of program memory.

;	Setur	NVMCON	for erase operation, multi wor	d	write
'	progr	MOV	#0x4041.W0	:	
		MOV	W0 NVMCON	;	Init NVMCON SFR
;	Init	pointer	to row to be ERASED		
		MOV	<pre>#tblpage(PROG_ADDR),W0</pre>	;	
		MOV	W0,NVMADRU	;	Initialize PM Page Boundary SFR
		MOV	<pre>#tbloffset(PROG_ADDR),W0</pre>	;	Intialize in-page EA[15:0] pointer
		MOV	W0, NVMADR	;	Initialize NVMADR SFR
		DISI	#5	;	Block all interrupts with priority <7 for
				;	next 5 instructions
		MOV	#0x55 <b>,</b> W0		
		MOV	W0,NVMKEY	;	Write the 0x55 key
		MOV	#OxAA,W1	;	
		MOV	W1,NVMKEY	;	Write the OxAA key
		BSET	NVMCON, #WR	;	Start the erase sequence
		NOP		;	Insert two NOPs after the erase
		NOP		;	command is asserted

**ERASING A ROW OF PROGRAM MEMORY** 

NOTES:

0000 0000 1111 1100 **Reset State** 0000 0011 0000 1111 **TRISG0** Bit 0 RG0 TRISG1 Bit 1 RG1 TRISG2 Bit 2 RG2 TRISG3 Bit 3 RG3 Bit 4 I I Bit 5 I PORTG REGISTER MAP FOR dsPIC30F6011A/6012A/6013A/6014A<sup>(1)</sup> **TRISG6** Bit 6 RG6 TRISG7 Bit 7 RG7 TRISG8 Bit 8 RG8 **FRISG9** Bit 9 RG9 Bit 10 Bit 11 TRISG12 Bit 12 RG12 TRISG13 Bit 13 RG13 TRISG14 Bit 14 RG14 **FRISG15** Bit 15 RG15 Addr. 02E4 02E6 PORTG SFR Name **FRISG** 

0000 0000 0000

0000

LATG0

LATG1

LATG2

LATG3

I

I

LATG6

LATG7

LATG8

LATG9 LATG12 LATG13 LATG14 LATG15 02E8 LATG

÷

u = uninitialized bit; — = unimplemented bit, read as '0' Refer to the "*dsPIC30F Family Reference Manual*" (DS70046) for descriptions of register bit fields. Note

**FABLE 8-9:** 

		nnn	111	0000	
	State	n nnnn	1111 1	0 0000	
	Reset	nnnn	1111	0000	
		nnnn	1111	0000	
	Bit 0			I	
	Bit 1			TCS	
	Bit 2			SYNC	
	- 			Ť	
	Bit				
	Bit 4			TCKPS	
	Bit 5			CKPS1	
	it 6			ATE T	
	ä	gister	ister 1	TG	
	Bit 7	Timer1 Re Period Reg	Ι		
	Bit 8		I		
	Bit 9		Ι		
	Bit 10			Ι	
_	Bit 11				d as '0'
ИАР <sup>(1</sup> .	3it 12				sd bit, rea
TER	:13 E			IDL	lemente
EGIS	14 Bit			TS	= unimp
R1 R	Bit 1				l bit; —
TIME	Bit 15			TON	nitializec
<del></del>	Addr.	0100	0102	0104	u = u
3LE 9-	R Name	-		NC	:pue
TAE	SFR	TMR	PR1	T1C(	Lege

Bit 0 Bit 1 ICM<2:0> ICM<2:0> Bit 2 Bit 3 ICBNE ICBNE ICOV ICOV Bit 4 Bit 5 ICI<1:0> ICI<1:0> Bit 6 ICTMR ICTMR Bit 7 Input 1 Capture Register Input 2 Capture Register Input 3 Capture Register Bit 8 I I Bit 9 I Bit 10 I I INPUT CAPTURE REGISTER MAP<sup>(1)</sup> Bit 11 L L Bit 12 I I Bit 13 ICSIDL ICSIDL Bit 14 I I Bit 15 T Addr. 0142 0144 0146 0148 0140 **TABLE 12-1**: SFR Name IC1CON IC2CON IC1BUF IC2BUF IC3BUF

Reset State

ICM<2:0>

ICOV ICBNE

ICI<1:0>

ICTMR

I

I

I

I

I

ICSIDL

I

I

014A 014C

IC3CON

Input 4 Capture Register

Input 5 Capture Register

ICM<2:0>

ICOV ICBNE

ICI<1:0>

ICTMR

I

I

I

I

I

ICSIDL

I

I

014E

IC4CON

IC4BUF

0150

IC5BUF

ICM<2:0>

ICBNE

ICOV

ICI<1:0>

ICTMR

I

I

I

I

I

ICSIDL

I

T

0152

IC5CON

0154 0156 0158

IC6BUF

Input 6 Capture Register

Input 7 Capture Register

Legend: u = uninitialized bit; — = unimplemented bit, read as '0' Note 1: Refer to the "*dsPlC30F Family Reference Manual*" (DS70046) for descriptions of register bit fields.

I

I

ICSIDL

I

I

015E

IC8CON

015C

IC8BUF

C	ls	s F	ן			30	)	=(	6	<b>D</b> '	11A/6012A/6013A/601
0000	uuuu	0000									
0000	nnnn	0000									
0000	nnnn	0000									
0000	nnnn	0000									

ICM<2:0>

ICBNE

ICOV

ICI<1:0>

ICTMR

I

I

L

I

I

ICSIDL

I

1

015A

IC7CON

IC7BUF

Input 8 Capture Register

ICM<2:0>

ICBNE

ICOV

ICI<1:0>

ICTMR

I

1

I

L

ICSIDL

I

T

ICECON

ICM<2:0>

ICBNE

ICOV

ICI<1:0>

ICTMR

## 13.4.2 PWM PERIOD

The PWM period is specified by writing to the PRx register. The PWM period can be calculated using Equation 13-1.

#### EQUATION 13-1:

$$PWM \ period = [(PRx) + 1] \cdot 4 \cdot TOSC \cdot (TMRx \ prescale \ value)$$

PWM frequency is defined as 1/[PWM period].

When the selected TMRx is equal to its respective period register, PRx, the following four events occur on the next increment cycle:

- TMRx is cleared
- The OCx pin is set
  - Exception 1: If PWM duty cycle is 0x0000, the OCx pin will remain low
  - Exception 2: If duty cycle is greater than PRx, the pin will remain high
- The PWM duty cycle is latched from OCxRS into OCxR
- The corresponding timer interrupt flag is set

See Figure 13-2 for key PWM period comparisons. Timer3 is referred to in Figure 13-2 for clarity.



I<sup>2</sup>C<sup>™</sup> REGISTER MAP<sup>(1)</sup> **TABLE 15-2**:

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset State
12CRCV	0200	I	I	Ι	1	1	I	1	I				Receive R	egister				0000 0000 0000 0000
<b>I2CTRN</b>	0202	Ι		Ι	Ι	I			Ι			-	<b>Fransmit R</b>	egister				0000 0000 1111 1111
12CBRG	0204	Ι		Ι	Ι	I						Baud R	ate Genera	ator				0000 0000 0000 0000
12CCON	0206	IZCEN		<b>I2CSIDL</b>	SCLREL	IPMIEN	A10M	DISSLW	SMEN	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	0001 0000 0000 0000
12CSTAT	0208	ACKSTAT	TRSTAT		Ι	I	BCL	GCSTAT	ADD10	IWCOL	I2COV	D_A	٩	S	R_W	RBF	TBF	0000 0000 0000 0000
12CADD	020A	Ι		Ι	Ι	Ι	I				1	Address R	egister					0000 0000 0000 0000
- huana l		nimnlemente	d hit read	,∪, se														

— – unimperimented but, read as ∪ Refer to the "dsPIC30F Family Reference Manual" (DS70046) for descriptions of register bit fields. ÷ Note

# 17.0 CAN MODULE

Note: This data sheet summarizes features of this group of dsPIC30F devices and is not intended to be a complete reference source. For more information on the CPU, peripherals, register descriptions and general device functionality, refer to the "dsPIC30F Family Reference Manual" (DS70046).

## 17.1 Overview

The Controller Area Network (CAN) module is a serial interface, useful for communicating with other CAN modules or microcontroller devices. This interface/ protocol was designed to allow communications within noisy environments.

The CAN module is a communication controller implementing the CAN 2.0 A/B protocol, as defined in the BOSCH specification. The module will support CAN 1.2, CAN 2.0A, CAN 2.0B Passive and CAN 2.0B Active versions of the protocol. The module implementation is a full CAN system. The CAN specification is not covered within this data sheet. The reader may refer to the BOSCH CAN specification for further details.

The module features are as follows:

- Implementation of the CAN protocol CAN 1.2, CAN 2.0A and CAN 2.0B
- Standard and extended data frames
- 0-8 bytes data length
- Programmable bit rate up to 1 Mbps
- · Support for remote frames
- Double-buffered receiver with two prioritized received message storage buffers (each buffer may contain up to 8 bytes of data)
- 6 full (standard/extended identifier) acceptance filters, 2 associated with the high priority receive buffer and 4 associated with the low priority receive buffer
- 2 full acceptance filter masks, one each associated with the high and low priority receive buffers
- Three transmit buffers with application specified prioritization and abort capability (each buffer may contain up to 8 bytes of data)
- Programmable wake-up functionality with integrated low-pass filter
- Programmable Loopback mode supports self-test operation
- Signaling via interrupt capabilities for all CAN receiver and transmitter error states
- · Programmable clock source
- Programmable link to Input Capture module (IC2, for both CAN1 and CAN2) for time-stamping and network synchronization
- Low-power Sleep and Idle mode

The CAN bus module consists of a protocol engine and message buffering/control. The CAN protocol engine handles all functions for receiving and transmitting messages on the CAN bus. Messages are transmitted by first loading the appropriate data registers. Status and errors can be checked by reading the appropriate registers. Any message detected on the CAN bus is checked for errors and then matched against filters to see if it should be received and stored in one of the receive registers.

## 17.2 Frame Types

The CAN module transmits various types of frames which include data messages or remote transmission requests initiated by the user, as other frames that are automatically generated for control purposes. The following frame types are supported:

Standard Data Frame:

A standard data frame is generated by a node when the node wishes to transmit data. It includes an 11-bit Standard Identifier (SID) but not an 18-bit Extended Identifier (EID).

· Extended Data Frame:

An extended data frame is similar to a standard data frame but includes an extended identifier as well.

• Remote Frame:

It is possible for a destination node to request the data from the source. For this purpose, the destination node sends a remote frame with an identifier that matches the identifier of the required data frame. The appropriate data source node will then send a data frame as a response to this remote request.

Error Frame:

An error frame is generated by any node that detects a bus error. An error frame consists of 2 fields: an error flag field and an error delimiter field.

· Overload Frame:

An overload frame can be generated by a node as a result of 2 conditions. First, the node detects a dominant bit during interframe space which is an illegal condition. Second, due to internal conditions, the node is not yet able to start reception of the next message. A node may generate a maximum of 2 sequential overload frames to delay the start of the next message.

· Interframe Space:

Interframe space separates a proceeding frame (of whatever type) from a following data or remote frame.

## 17.4 Message Reception

#### 17.4.1 RECEIVE BUFFERS

The CAN bus module has 3 receive buffers. However, one of the receive buffers is always committed to monitoring the bus for incoming messages. This buffer is called the Message Assembly Buffer (MAB). So there are 2 receive buffers visible, RXB0 and RXB1, that can essentially instantaneously receive a complete message from the protocol engine.

All messages are assembled by the MAB and are transferred to the RXBn buffers only if the acceptance filter criterion are met. When a message is received, the RXnIF flag (CiINTF<0> or CiINRF<1>) will be set. This bit can only be set by the module when a message is received. The bit is cleared by the CPU when it has completed processing the message in the buffer. If the RXnIE bit (CiINTE<0> or CiINTE<1>) is set, an interrupt will be generated when a message is received.

RXF0 and RXF1 filters with RXM0 mask are associated with RXB0. The filters RXF2, RXF3, RXF4, and RXF5 and the mask RXM1 are associated with RXB1.

#### 17.4.2 MESSAGE ACCEPTANCE FILTERS

The message acceptance filters and masks are used to determine if a message in the message assembly buffer should be loaded into either of the receive buffers. Once a valid message has been received into the Message Assembly Buffer (MAB), the identifier fields of the message are compared to the filter values. If there is a match, that message will be loaded into the appropriate receive buffer.

The acceptance filter looks at incoming messages for the RXIDE bit (CiRXnSID<0>) to determine how to compare the identifiers. If the RXIDE bit is clear, the message is a standard frame and only filters with the EXIDE bit (CiRXFnSID<0>) clear are compared. If the RXIDE bit is set, the message is an extended frame, and only filters with the EXIDE bit set are compared. Configuring the RXM<1:0> bits to '01' or '10' can override the EXIDE bit.

#### 17.4.3 MESSAGE ACCEPTANCE FILTER MASKS

The mask bits essentially determine which bits to apply the filter to. If any mask bit is set to a zero, then that bit will automatically be accepted regardless of the filter bit. There are 2 programmable acceptance filter masks associated with the receive buffers, one for each buffer.

#### 17.4.4 RECEIVE OVERRUN

An overrun condition occurs when the Message Assembly Buffer (MAB) has assembled a valid received message, the message is accepted through the acceptance filters and when the receive buffer associated with the filter has not been designated as clear of the previous message.

The overrun error flag, RXnOVR (CiINTF<15> or CiINTF<14>), and the ERRIF bit (CiINTF<5>) will be set and the message in the MAB will be discarded.

If the DBEN bit is clear, RXB1 and RXB0 operate independently. When this is the case, a message intended for RXB0 will not be diverted into RXB1 if RXB0 contains an unread message and the RX00VR bit will be set.

If the DBEN bit is set, the overrun for RXB0 is handled differently. If a valid message is received for RXB0 and RXFUL = 1 indicates that RXB0 is full and RXFUL = 0 indicates that RXB1 is empty, the message for RXB0 will be loaded into RXB1. An overrun error will not be generated for RXB0. If a valid message is received for RXB0 and RXFUL = 1, indicating that both RXB0 and RXB1 are full, the message will be lost and an overrun will be indicated for RXB1.

#### 17.4.5 RECEIVE ERRORS

The CAN module will detect the following receive errors:

- Cyclic Redundancy Check (CRC) Error
- Bit Stuffing Error
- Invalid Message Receive Error

The receive error counter is incremented by one in case one of these errors occur. The RXWAR bit (CiINTF<9>) indicates that the receive error counter has reached the CPU warning limit of 96 and an interrupt is generated.

#### 17.4.6 RECEIVE INTERRUPTS

Receive interrupts can be divided into 3 major groups, each including various conditions that generate interrupts:

· Receive Interrupt:

A message has been successfully received and loaded into one of the receive buffers. This interrupt is activated immediately after receiving the End of Frame (EOF) field. Reading the RXnIF flag will indicate which receive buffer caused the interrupt.

• Wake-up Interrupt:

The CAN module has woken up from Disable mode or the device has woken up from Sleep mode.

# 19.0 12-BIT ANALOG-TO-DIGITAL CONVERTER (ADC) MODULE

Note: This data sheet summarizes features of this group of dsPIC30F devices and is not intended to be a complete reference source. For more information on the CPU, peripherals, register descriptions and general device functionality, refer to the "dsPIC30F Family Reference Manual" (DS70046).

The 12-bit Analog-to-Digital Converter (ADC) allows conversion of an analog input signal to a 12-bit digital number. This module is based on a Successive Approximation Register (SAR) architecture and provides a maximum sampling rate of 200 ksps. The ADC module has up to 16 analog inputs which are multiplexed into a sample and hold amplifier. The output of the sample and hold is the input into the converter which generates the result. The analog reference voltage is software selectable to either the device supply voltage (AVDD/AVSS) or the voltage level on the (VREF+/VREF-) pin. The ADC has a unique feature of being able to operate while the device is in Sleep mode with RC oscillator selection. The ADC module has six 16-bit registers:

- ADC Control Register 1 (ADCON1)
- ADC Control Register 2 (ADCON2)
- ADC Control Register 3 (ADCON3)
- ADC Input Select Register (ADCHS)
- ADC Port Configuration Register (ADPCFG)
- ADC Input Scan Selection Register (ADCSSL)

The ADCON1, ADCON2 and ADCON3 registers control the operation of the ADC module. The ADCHS register selects the input channels to be converted. The ADPCFG register configures the port pins as analog inputs or as digital I/O. The ADCSSL register selects inputs for scanning.

Note: The SSRC<2:0>, ASAM, SMPI<3:0>, BUFM and ALTS bits, as well as the ADCON3 and ADCSSL registers, must not be written to while ADON = 1. This would lead to indeterminate results.

The block diagram of the 12-bit ADC module is shown in Figure 19-1.





# FIGURE 19-3: CONVERTING 1 CHANNEL AT 200 KSPS, AUTO-SAMPLE START, 1 TAD SAMPLING TIME



## **19.8 ADC Acquisition Requirements**

The analog input model of the 12-bit ADC is shown in Figure 19-4. The total sampling time for the ADC is a function of the internal amplifier settling time and the holding capacitor charge time.

For the ADC to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the voltage level on the analog input pin. The source impedance (Rs), the interconnect impedance (RIC) and the internal sampling switch (Rss) impedance combine to directly affect the time required to charge the capacitor CHOLD. The combined impedance of the analog sources must therefore be small enough to fully charge the holding capacitor within the chosen sample time. To minimize the effects of pin leakage currents on the accuracy of the ADC, the maximum recommended source impedance, Rs, is 2.5 k $\Omega$  After the analog input channel is selected (changed), this sampling function must be completed prior to starting the conversion. The internal holding capacitor will be in a discharged state prior to each sample operation.

#### FIGURE 19-4: 12-BIT ADC ANALOG INPUT MODEL



# 23.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC30F electrical characteristics. Additional information will be provided in future revisions of this document as it becomes available.

For detailed information about the dsPIC30F architecture and core, refer to "dsPIC30F Family Reference Manual" (DS70046).

Absolute maximum ratings for the dsPIC30F family are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

# Absolute Maximum Ratings<sup>(†)</sup>

Ambient temperature under bias	40°C to +125°C
Storage temperature	65°C to +150°C
Voltage on any pin with respect to Vss (except VDD and MCLR) <sup>(1)</sup>	0.3V to (VDD + 0.3V)
Voltage on VDD with respect to Vss	0.3V to +5.5V
Voltage on MCLR with respect to Vss	0V to +13.25V
Maximum current out of Vss pin	
Maximum current into VDD pin <sup>(2)</sup>	250 mA
Input clamp current, IIK (VI < 0 or VI > VDD)	±20 mA
Output clamp current, IOK (VO < 0 or VO > VDD)	±20 mA
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	25 mA
Maximum current sunk by all ports	200 mA
Maximum current sourced by all ports <sup>(2)</sup>	200 mA
<b>Note 1:</b> Voltage spikes below Vss at the $\overline{\text{MCLR}}$ /VPP pin, inducing currents greater than 80 Thus, a series resistor of 50-100 $\Omega$ should be used when applying a "low" level to than pulling this pin directly to Vss.	0 mA <u>, may</u> cause latchup. the MCLR/VPP pin, rather

2: Maximum allowable current is a function of device maximum power dissipation. See Table 23-2 for PDMAX.

**†NOTICE:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

## FIGURE 23-8: TYPE A, B AND C TIMER EXTERNAL CLOCK TIMING CHARACTERISTICS



# TABLE 23-23: TYPE A TIMER (TIMER1) EXTERNAL CLOCK TIMING REQUIREMENTS<sup>(1)</sup>

АС СНА	RACTERIST	ICS		<b>Standa</b> (unless Operat	ord Operating ( s otherwise stating temperatur	Conditio ated) e -40° -40°	ONS: 2.5\ C ≤TA ≤+; C ≤TA ≤+;	/ to 5.5V 85°C for 125°C fo	ndustrial pr Extended
Param No.	Symbol	Charact	eristic		Min	Тур	Мах	Units	Conditions
TA10	ТтхН	TxCK High Time	Synchro no preso	nous, caler	0.5 TCY + 20			ns	Must also meet parameter TA15
			Synchro with pres	nous, scaler	10		—	ns	
			Asynchr	onous	10		_	ns	
TA11	ΤτxL	TxCK Low Time	Synchro no preso	nous, caler	0.5 TCY + 20		—	ns	Must also meet parameter TA15
			Synchro with pres	nous, scaler	10		_	ns	
			Asynchr	onous	10		—	ns	
TA15	ΤτχΡ	TxCK Input Period	Synchro no preso	nous, caler	Tcy + 10	_	—	ns	
			Synchro with pres	nous, scaler	Greater of: 20 ns or (TCY + 40)/N	_	_	-	N = prescale value (1, 8, 64, 256)
			Asynchr	onous	20		—	ns	
OS60	Ft1	SOSC1/T1CK oscil frequency range (or by setting bit TCS (	llator inpu scillator e T1CON,	it enabled bit 1))	DC	—	50	kHz	
TA20	TCKEXTMRL	Delay from Externa Edge to Timer Incre	II TxCK C ement	lock	0.5 TCY	_	1.5 Тсү	—	

Note 1: Timer1 is a Type A.

#### TABLE 23-35: I<sup>2</sup>C<sup>™</sup> BUS DATA TIMING REQUIREMENTS (MASTER MODE)

АС СНА	ARACTER	ISTICS		Standard Operatir (unless otherwise Operating tempera	<b>stated)</b> ture -40 -40	:ions: 2.5\ )°C ≤Ta ≤+ )°C ≤Ta ≤+	<b>V to 5.5V</b> 85°C for Industrial 125°C for Extended
Param No.	Symbol	Charac	teristic	Min <sup>(1)</sup>	Max	Units	Conditions
IM10	TLO:SCL	Clock Low Time	100 kHz mode	Tcy / 2 (BRG + 1)	_	μs	
			400 kHz mode	Tcy / 2 (BRG + 1)	_	μs	
			1 MHz mode <sup>(2)</sup>	TCY / 2 (BRG + 1)	_	μs	
IM11	THI:SCL	Clock High Time	100 kHz mode	Tcy / 2 (BRG + 1)	_	μs	
			400 kHz mode	Tcy / 2 (BRG + 1)	_	μs	
			1 MHz mode <sup>(2)</sup>	TCY / 2 (BRG + 1)	_	μs	
IM20	TF:SCL	SDA and SCL	100 kHz mode	—	300	ns	CB is specified to be
		Fall Time	400 kHz mode	20 + 0.1 Св	300	ns	from 10 to 400 pF
			1 MHz mode <sup>(2)</sup>	_	100	ns	
IM21	TR:SCL	SDA and SCL	100 kHz mode	—	1000	ns	CB is specified to be
		Rise Time	400 kHz mode	20 + 0.1 Св	300	ns	from 10 to 400 pF
			1 MHz mode <sup>(2)</sup>	—	300	ns	
IM25	TSU:DAT	Data Input	100 kHz mode	250	_	ns	
		Setup Time	400 kHz mode	100	_	ns	
			1 MHz mode <sup>(2)</sup>	_	_	ns	
IM26	THD:DAT	Data Input	100 kHz mode	0	_	ns	
		Hold Time	400 kHz mode	0	0.9	μs	
			1 MHz mode <sup>(2)</sup>	—	_	ns	
IM30 Tsu:sta		Start Condition	100 kHz mode	TCY / 2 (BRG + 1)	_	μs	Only relevant for
		Setup Time	400 kHz mode	Tcy / 2 (BRG + 1)	_	μs	repeated Start
IM31 THD'ST			1 MHz mode <sup>(2)</sup>	TCY / 2 (BRG + 1)	_	μs	condition
IM31 THD:STA		Start Condition	100 kHz mode	Tcy / 2 (BRG + 1)	_	μs	After this period the
		Hold Time	400 kHz mode	Tcy / 2 (BRG + 1)	—	μs	first clock pulse is
			1 MHz mode <sup>(2)</sup>	Tcy / 2 (BRG + 1)		μs	generated
IM33	3 TSU:STO Stop Condition		100 kHz mode	Tcy / 2 (BRG + 1)	_	μs	
IM33 ISU:STO		Setup Time	400 kHz mode	TCY / 2 (BRG + 1)		μs	
			1 MHz mode <sup>(2)</sup>	TCY / 2 (BRG + 1)		μs	
IM34	THD:STO	Stop Condition	100 kHz mode	TCY / 2 (BRG + 1)		ns	
		Hold Time	400 kHz mode	TCY / 2 (BRG + 1)		ns	
			1 MHz mode <sup>(2)</sup>	Tcy / 2 (BRG + 1)		ns	
IM40	TAA:SCL	Output Valid	100 kHz mode	—	3500	ns	
		From Clock	400 kHz mode	_	1000	ns	
			1 MHz mode <sup>(2)</sup>	—	_	ns	
IM45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	_	μs	Time the bus must be
			400 kHz mode	1.3		μs	tree before a new
			1 MHz mode <sup>(2)</sup>			μs	transmission can start
IM50	Св	Bus Capacitive L	oading	—	400	pF	

Note 1: BRG is the value of the I<sup>2</sup>C<sup>™</sup> Baud Rate Generator. Refer to Section 21. "Inter-Integrated Circuit™ (I<sup>2</sup>C)" (DS70046) in the "*dsPIC30F Family Reference Manual*".
 2: Maximum pin capacitance = 10 pF for all I<sup>2</sup>C pins (for 1 MHz mode only).

#### TABLE 23-39: 12-BIT ADC TIMING REQUIREMENTS

АС СНА		STICS	Standard (unless of Operatin	d Operatin otherwise g tempera	ng Cond e stated) ature -4	itions: 2.7 10°C ≤Ta ≤ 10°C ≤Ta ≤	<b>'V to 5.5V</b> +85°C for Industrial +125°C for Extended
Param No.	Symbol	Characteristic	Min.	Тур	Max.	Units	Conditions
		Cloc	k Parame	ters			
AD50	TAD	ADC Clock Period	_	334	_	ns	VDD = 3-5.5V (Note 1)
AD51	tRC	ADC Internal RC Oscillator Period	1.2	1.5	1.8	μs	
	-	Con	version R	ate			
AD55	tCONV	Conversion Time	_	14 Tad		ns	
AD56	FCNV	Throughput Rate		200		ksps	VDD = VREF = 3-5.5V
AD57	TSAMP	Sample Time	_	1 Tad	_	ns	$V_{DD}$ = 3-5.5V Source resistance Rs = 0-2.5 k $\Omega$
		Timin	g Parame	eters			
AD60	tPCS	Conversion Start from Sample Trigger		1 Tad		ns	
AD61	tPSS	Sample Start from Setting Sample (SAMP) Bit	0.5 Tad		1.5 Tad	ns	
AD62	tcss	Conversion Completion to Sample Start (ASAM = 1)		0.5 TAD	—	ns	
AD63	tdpu <sup>(2)</sup>	Time to Stabilize Analog Stage from ADC Off to ADC On		_	20	μs	

**Note 1:** Because the sample caps will eventually lose charge, clock rates below 10 kHz can affect linearity performance, especially at elevated temperatures.

2: tDPU is the time required for the ADC module to stabilize when it is turned on (ADCON1<ADON> = 1). During this time the ADC result is indeterminate.